

Single P-Channel MOSFET

DESCRIPTION

SMC3251SN is the P-Channel trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

PART NUMBER INFORMATION

SMC 3251 SN - TR G
 a b c d e

- a : Company name.
- b : Product Serial number.
- c : Package code SN: SOT-23
- d : Handling code TR: Tape&Reel
- e : Green produce code G: *RoHS Compliant*

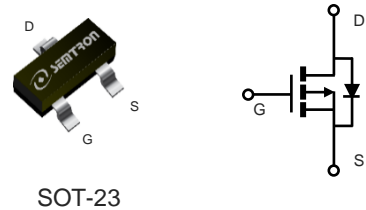
FEATURES

$V_{DS}=-30V$, $I_D=-3.7A$

$R_{DS(ON)}=56m\Omega(Typ.)@V_{GS}=-10V$
 $R_{DS(ON)}=80m\Omega(Typ.)@V_{GS}=-4.5V$

APPLICATIONS

- ◆ Portable Equipment
- ◆ Power Management
- ◆ Load Switch



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ Unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|-----------|---------------------------------------|------------------|------------|
| V_{DSS} | Drain-Source Voltage | -30 | V |
| V_{GSS} | Gate-Source Voltage | ± 20 | V |
| I_D | Continuous Drain Current ^A | $T_A=25^\circ C$ | -3.7 |
| | | $T_A=70^\circ C$ | -2.9 |
| I_{DM} | Pulsed Drain Current ^B | -14.8 | A |
| P_D | Power Dissipation ^A | $T_A=25^\circ C$ | 1.3 |
| | | $T_A=70^\circ C$ | 0.8 |
| T_J | Operation Junction Temperature | -55/150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55/150 | $^\circ C$ |

THERMAL RESISTANCE

| Symbol | Parameter | Typ | Max | Units |
|-----------------|--|--------------|-----|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient ^A | $t \leq 10s$ | 95 | $^\circ C/W$ |
| | Thermal Resistance Junction to Ambient ^{AC} | Steady-State | 130 | |

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ Unless otherwise noted)

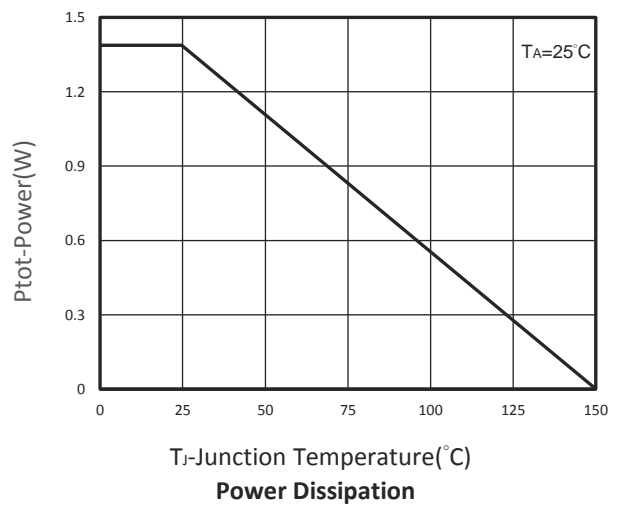
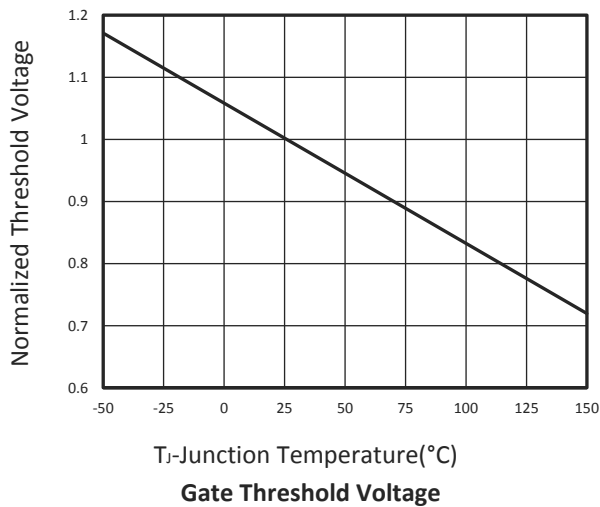
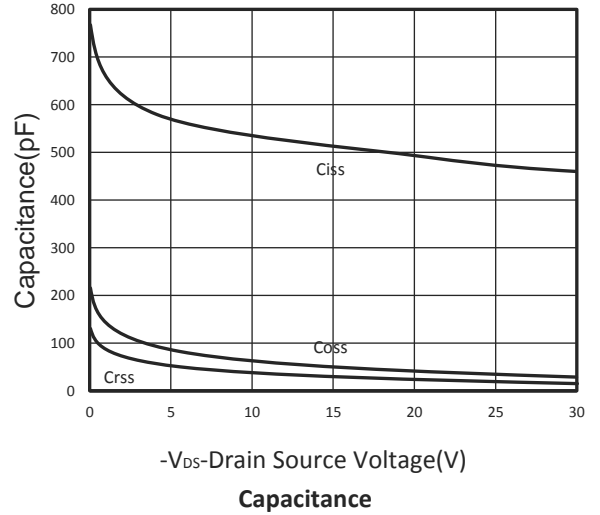
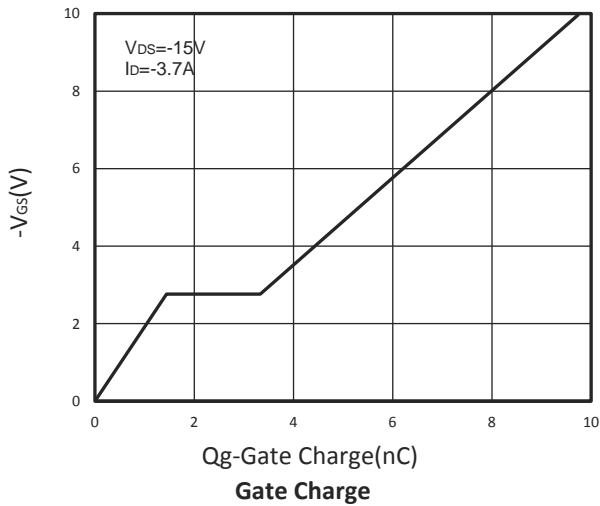
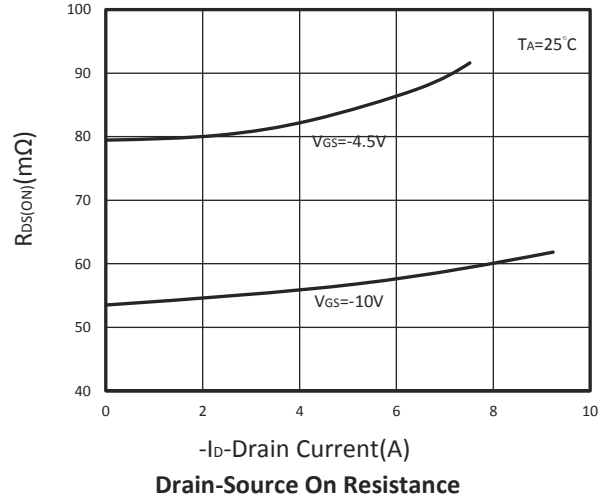
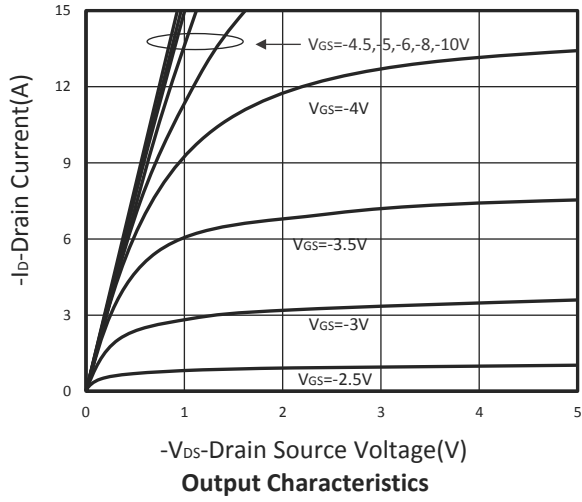
| Symbol | Parameter | Condition | Min | Typ | Max | Unit |
|--|---|---|-----|----------|-----------|------------|
| Static Parameters | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250 μ A | -30 | | | V |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =-250 μ A | -1 | -1.6 | -2 | V |
| I _{GSS} | Gate Leakage Current | V _{DS} =0V, V _{GS} = \pm 20V | | | \pm 100 | nA |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =-30V, V _{GS} =0V, T _J =25 $^\circ$ C | | | -1 | μ A |
| | | V _{DS} =-24V, V _{GS} =0V, T _J =75 $^\circ$ C | | | -10 | |
| R _{DS(ON)} | Drain-source On-Resistance ^D | V _{GS} =-10V, I _D =-3.7A V _{GS} =-4.5V, I _D =-2.3A | | 56 80 | 65 95 | m Ω |
| G _{fs} | Forward Transconductance | V _{DS} =-10V, I _D =-3.7A | | 6.5 | | S |
| Diode Characteristics | | | | | | |
| V _{SD} | Diode Forward Voltage ^D | I _S =-1A, V _{GS} =0V | | | -1 | V |
| I _S | Diode Continuous Forward Current | | | | -3.7 | A |
| Dynamic and Switching Parameters ^E | | | | | | |
| Q _g | Total Gate Charge | V _{DS} =-15V, V _{GS} =-10V I _D =-3.7A | | 9.8 | 13.8 | nC |
| Q _g | Total Gate Charge (4.5V) | | | 4.8 | 6.7 | |
| Q _{gs} | Gate-Source Charge | | | 1.7 | 2 | |
| Q _{gd} | Gate-Drain Charge | | | 2 | 2.8 | |
| C _{iss} | Input Capacitance | V _{DS} =-15V, V _{GS} =0V, f =1MHz | | 510 | | pF |
| C _{oss} | Output Capacitance | | | 48 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 31 | | |
| t _{d(on)} | Turn-On Time | V _{DD} =-15V, V _{GEN} =-10V R _G =3.3 Ω , I _D =-1A | | 3.2 | 6 | nS |
| t _r | | | | 9.5 | 18 | |
| t _{d(off)} | Turn-Off Time | | | 16 | 30 | |
| t _f | | | | 5.7 | 11 | |

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

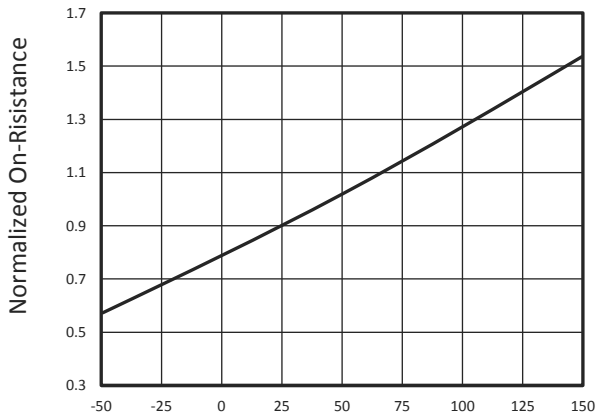
- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, T_{J(MAX)}=150 $^\circ$ C (initial temperature T_J=25 $^\circ$ C).
- C. Using \leq 10s junction-to-ambient thermal resistance is base on T_{J(MAX)}=150 $^\circ$ C.
- D. Pulse test width \leq 300 μ s and duty cycle \leq 2%.
- E. Guaranteed by design, not subject to production testing.

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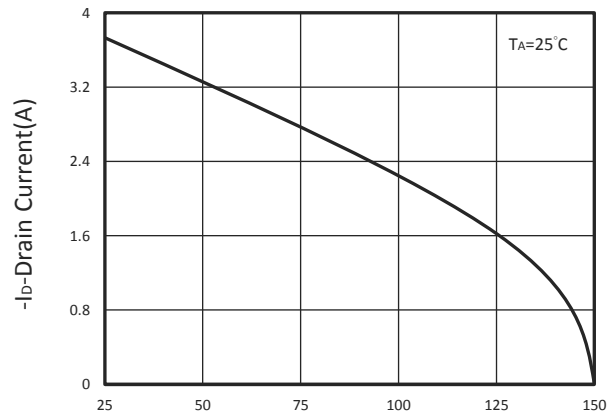
TYPICAL CHARACTERISTICS



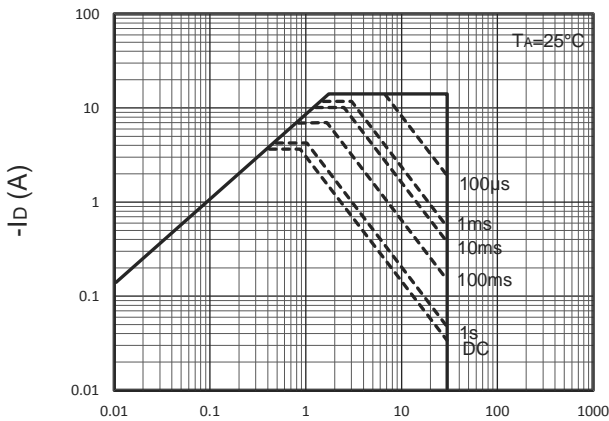
TYPICAL CHARACTERISTICS



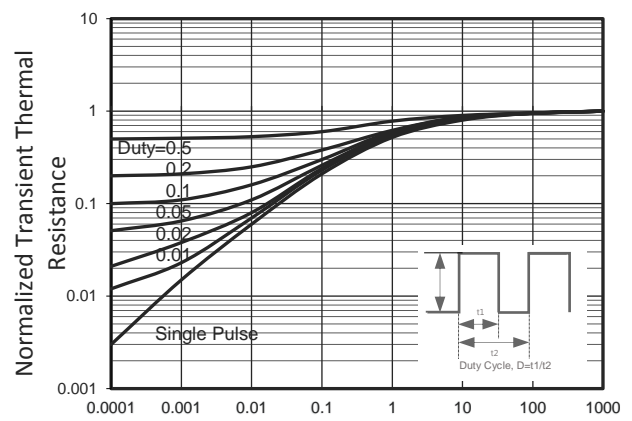
T_J-Junction Temperature(°C)
Drain-Source On Resistance



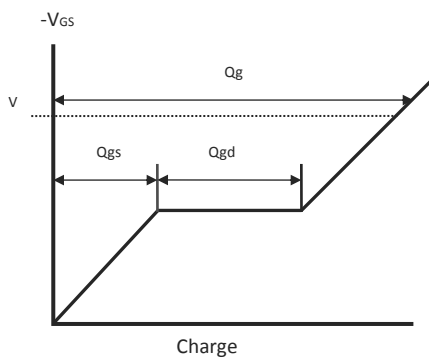
T_J-Junction Temperature(°C)
Drain Current vs T_J



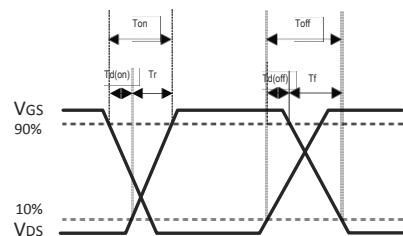
- V_{ds} Voltage (V)
Maximum Safe Operation Area



Square Wave Pulse Duration(Sec)
Thermal Transient Impedance

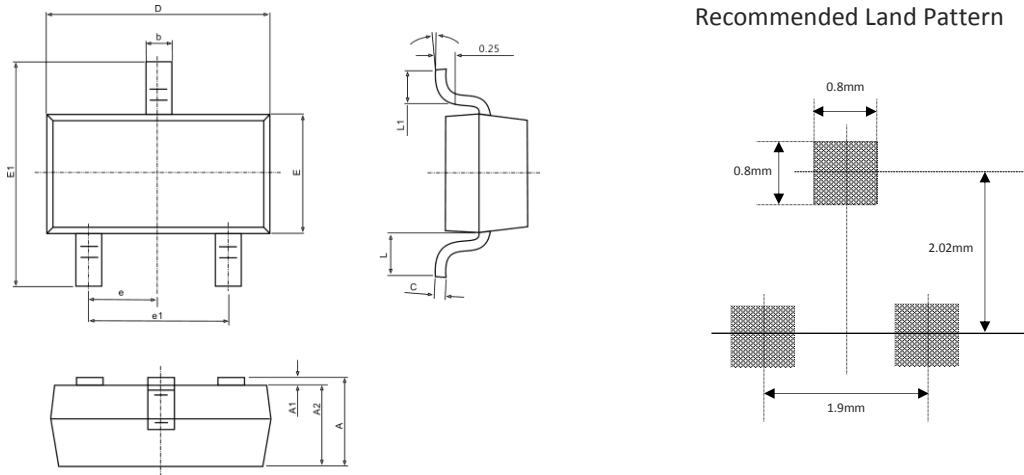


Gate Chrg Waveform



Switching Time Waveform

■ SOT-23 PACKAGE DIMENSIONS



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.940 | 1.120 | 0.037 | 0.044 |
| A1 | 0.040 | 0.120 | 0.002 | 0.005 |
| A2 | 0.900 | 1.000 | 0.035 | 0.039 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.090 | 0.110 | 0.004 | 0.004 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 BSC | | 0.037 BSC | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.500 | 0.600 | 0.020 | 0.024 |
| L | 0.550 BSC | | 0.022 BSC. | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 |
| θ | 1° | 7° | 1° | 7° |